Product iQ®

Wiring, Printed - Flexible Material Constructions - Component

COMPANY
BASELECTRON SRL
Via Mons. Angelini 18
San Martino Siccomario, PV 27028 Italy

E477015

Type	Cond Width Min mm	Min Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report Date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Solder Process Cycles	Solder Limits °C	Solder Limits sec	Max Oper Temp °C	Flame Class	Meets UL796F DSR	C T I
Multilayer flexible materials interconnect constructions (Flexible Application)															
FM	0.09	0.09	12 Int:35	DS	50.8	No	-	-	-	288	20	105	V-0	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions (Flexible Application)															
RF	0.09	0.09	35 Int:35	DS	50.8	No	-	-	-	288	10	120	V-0	-	-
Single layer flexible materials interconnect constructions(Flexible Application)															
F	0.09	0.09	12	DS	50.8	No	-	-	-	288	20	105	V-0	-	-

Marking: Company nameor file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2022-06-16

UL Solutions permits the reproduction of the material contained in Product iQ subject to the following conditions: 1. The Guide Information, Assemblies, Constructions, Designs, Systems, and/or Certifications (files) must be presented in their entirety and in a non-misleading manner, without any manipulation of the data (or drawings). 2. The statement "Reprinted from Product iQ with permission from UL Solutions" must appear adjacent to the extracted material. In addition, the reprinted material must include a copyright notice in the following format: "©2026 UL LLC."